





Receptacle: Horizontal type

Receptacle: Vertical type

Compliance with RoHS Directive

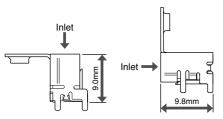
FEATURES

1. High-level impedance matching performance based on HDMI Standards

2. Space-saving size

Horizontal type: 9.8 mm in depth Vertical type: 9.0 mm in height Horizontal type

Vertical type



COMPATIBLE WITH HDMI STANDARD

3. Horizontal and vertical type receptacles are usable on the same foot pattern.

Either the horizontal or vertical type can be used on the same printed circuit board, reducing the design cost and the number of components to be controlled in the target equipment.

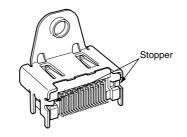
4. Shell having a GND structure for **EMI prevention**

The screw flange and the metal clips have enhanced grounding performance.



DIP terminal metal clips

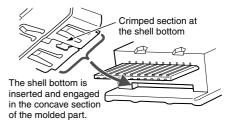
5. Structure with high resistance to the excessive press-in force of a plug



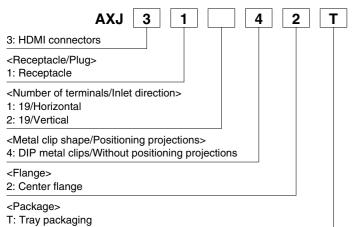
HDMI CONNECTORS

6. Structure with high resistance to twisting forces

The resistance has been increased by adopting a structure with a screw flange and DIP terminal metal clips fixed to the housing and circuit board, crimping the shell bottom, and holding it with the molded part.



ORDERING INFORMATION



PRODUCT TYPES

Number of terminals	Inlet direction	Part No.	Packing quantity	
Number of terminals			Inner carton (tray)	Outer carton
19 terminals	Horizontal type	AXJ31142T	100	1,000
	Vertical type	AXJ31242T	100	

SPECIFICATIONS

1. Characteristics

	Item	Specifications	Test conditions
	Rated current	0.5 A/terminal	
Electrical characteristics	Rated voltage	40V AC (rms.)	FIA 264.00 (Event wire conductor registered)
	Contact resistance	Contact: Max. 50mΩ Shell: Max. 50mΩ	EIA-364-23 (Except wire conductor resistance) EIA-364-06A-83
	Dielectric withstanding voltage	Unmated: Apply 500V AC for 1minute between adjacent terminal or ground. No breakdown. Mated: Apply 300V AC for 1minute between adjacent terminal or ground. No breakdown.	EIA-364-20 Detection current: 1mA
	Insulation resistance	Unmated: Min. 100M Ω between adjacent terminal or ground. Mated: Min. 10M Ω between adjacent terminal or ground.	EIA-364-21 Unmated: Using 500V DC megger Mated: Using 150V DC megger
	Electrostatic discharge	No evidence of discharge to contacts at 8 kV	IEC-801-2 Test unmated connector from 1 kV to 8 kV in 1 kV steps using 8 mm probe.
	T.M.D.S Impedance	$100\Omega \pm 15\%$	EIA-364-108 Draft Proposal Rise time: 200 p sec. (10% to 90%) Differential measurement specimen environment impedance: 100Ω differential Source-side receptacle connector mounted on a controlled impedance PCB fixture.
	T.M.D.S Cross talk FEXT	Max. 5 % (Max. –26 dB)	EIA-364-90 Draft Proposal Rise time: 200 p sec. (10% to 90%) Differential measurement specimen environment impedance: 100Ω differential Source-side receptacle connector mounted on a controlled impedance PCB fixture. Driven pair and victim pair.
	Insertion force (initial)	Max. 44.1N {4.5kg}	EIA-364-13 Mate and un-mate connector at maximum rate of 25mm per minute
	Removal force (initial)	Min. 9.8N {1.0kg}, Max. 39.2N {4.0kg}	EIA-364-13 Mate and un-mate connector at maximum rate of 25mm per minute
Mechanical characteristics	Screw tightening torque	Use M3 screw Recommended torque: 0.294N-m {3.0kgf-cm} Max. permissible torque: 0.343N-m {3.5kgf-cm}	Put the connector to PC board, then tighten the screw at following torque.
	Durability	After 10,000 cycles Contact resistance: Change from initial requirement Contact: Max. $30m\Omega$ Shell: Max. $50m\Omega$	100±50 cycles per hour
	Ambient temperature	0°C to +50°C	No freezing or condensation
Environmental characteristics	Storage condition	-20°C to +60°C (-20°C to +50°C for packaging materials)	No freezing or condensation
	Vibration	Appearance: No breakdown Contact resistance: Change from initial requirement Contact: Max. 30mΩ Shell: Max. 50mΩ Discontinuity: Max. 1μsec	EIA-364-28 Method 5A Amplitude: 1.52 mm P-P or 147 m/s ² (15G) Sweep time: 50-2000-50 Hz in 20 minutes Duration: 12 times in each (total of 36 times) X, Y, Z axes. Electrical load: 100 mA DC current shall be flowed during the test.
	Physical shock	Appearance: No breakdown Contact resistance: Change from initial requirement Contact: Max. 30mΩ Shell: Max. 50mΩ Discontinuity: Max. 1µsec	EIA-364-27 Condition A Pulse width: 11msec Wave form: half sine 490 m/s ² (50 G) Direction: 6 sides (X, Y, Z direction) Number of impacts: 3 times each (total 18 times)
	Thermal shock (mating)	After 10 cycles Appearance: No breakdown Contact resistance: Change from initial requirement Contact: Max. 30mΩ Shell: Max. 50mΩ	EIA-364-32 Condition I Order Temperature Time (min.) 1 -55±3°C 30 2 ~ Max. 5 3 85±2°C 30 4 ~ Max. 5
	Humidity resistance A (mating)	After 4 cycles (96 hours) Appearance: No breakdown Contact resistance: Change from initial requirement Contact: Max. 30mΩ Shell: Max. 50mΩ	EIA-364-31 Mate connectors and expose to humidity at figure1. Temperature: +25°C to +85°C Relative humidity: 80 to 95% Upon completion of the test specimens shall be conditioned a ambient room conditions for 24 hours, after which the specifier measurements shall be performed.
	Humidity resistance B (unmating)	After 4 cycles (96 hours) Appearance: No breakdown Dielectric withstanding voltage: Must meet dielectric withstanding voltage of electrical characteristics Insulation resistance: Must meet contact resistance of electrical characteristics	EIA-364-31 Unmate connectors and expose to humidity at figure1. Temperature: +25°C to +85°C Relative humidity: 80 to 95% Upon completion of the test specimens shall be conditioned a ambient room conditions for 24 hours, after which the specifie measurements shall be performed.
	Heat resistance (mating)	After 250 hours Appearance: No breakdown Contact resistance: Change from initial requirement Contact: Max. 30mΩ Shell: Max. 50mΩ	EIA-364-17 Under mating condition Temperature: 105°C±2°C Upon completion of the test specimens shall be conditioned a ambient room conditions for 1 to 2 hours, after which the
		01011. Max. 301122	specified measurements shall be performed.
Soldering emperature	Reflow soldering	Peak temperature: Max. 260°C	specified measurements shall be performed.

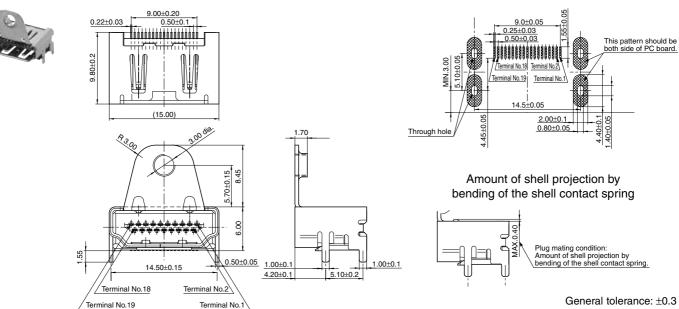
2. Material and surface treatment

Part name		Material	Surface treatment
Receptacle	Molded portion	LCP resin (UL94V-0), Color: Black	-
	Post	Copper alloy	Contact portion: Au flash plating on PdNi over Ni Terminal portion: Au flash plating over Ni (except for top of the terminal)
	Shell	Copper alloy	Sn plating over Ni

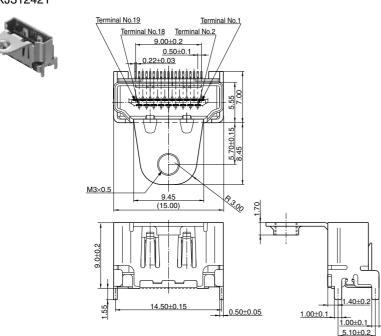
DIMENSIONS (Unit: mm)

• Receptacle: Horizontal type



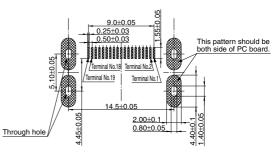


Receptacle: Vertical type AXJ31242T

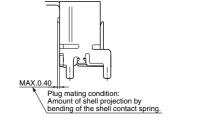


Recommended board pattern (Reference)

Recommended board pattern (Reference)



Amount of shell projection by bending of the shell contact spring



General tolerance: ±0.3

NOTES

 A cover for receptacle is recommended to prevent dusts.
 Regarding PC board design Refer the recommended PC board

pattern for keeping the strength of soldering.

3. Regarding soldering

1) Manual soldering

Please use the soldering iron under specification's temperature and times.
In case of exercise care not to contaminate the contacts with solder flux from the soldering iron tip. And make sure that the contacts are not contaminated to dispersed solder flux with a magnifying glass and so on.
Please pay attentions. Not to deform terminals when apply an excessive force to terminals, or the posts.

Please soldering iron is cleaning.2) Reflow soldering

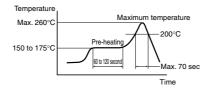
• Please use screen soldering regarding cream solder printing.

• A screen thickness of 0.15 mm is recommended during cream solder printing.

• When applying the different thickness of a screen, please consult us.

• There may be a case of difficult selfalignment depending on the connector size. In that case, please pay attentions to align terminals and solder pads. • The following diagram shows the recommended reflow soldering temperature profile.

The recommended conditions for the reflow temperature profile



The temperature measured on the PC board surface near connector terminals.
After reflow soldering, in case of PC board surface the reverse side using reflow soldering, for example an adhesive and so on connector of fixed disposition.
After soldering, we recommend the solder of the addition to the terminal dip of the shell for the strength securing.

4. Rework of soldering portion1) Rework is one time.

 2) In case of soldering rework of bridges.
 2) Please use a flat-head soldering iron and don't use supplementary solder flux.
 3) Please use the soldering iron under specification's temperature.

5. Since excessive force on the terminals will cause deformation and the integrity of the soldering will be lost during reflow soldering, avoid dropping or rough handling of the product.

6. PC board warpage should be controlled to 0.03 mm max. after soldering to a PC board. 7. Repeated bending of terminals and holding parts can result in terminals breaking.

8. Please do the screw tightening of the flange by the tightening torque below recommended torque. Please note that tightening more than

the permissible limit torque has danger of causing the transformation of the shell.

9. Regarding after soldering connectors on PC boards

 After mounting connectors on PC boards, do not apply excessive loads to the connector by piling up the boards.
 Please do not add the force to the connector during assembled connector on PC board.

10. This connector has metal shell for preventing EMI, when designing an enclosure the followings should be considered. Guide for plug entrance should be arranged in order to prevent distorted insertions. Provide a cover to reinforce the metal shell portions of the receptacle.

11. Other notes

After soldering is no coating. In case of using coating, please do not stick to the terminal.

For other details, please verify with the product specification sheets.

单击下面可查看定价,库存,交付和生命周期等信息

>>Panasonic(松下)